



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D * : Required Field

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2018-02-06
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Authorized Representative *	Floriana SAN BIAGIO	Representative Title	AMS MD CHAMPION
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement


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Legal Statement			
Supplier Acceptance *	true	Legal Declaration *	Standard

Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
	MYYG*UT88AA6	B	SA1A	2018-02-06
Amount	UoM	Unit type	ST ECOPACK Grade	
24.40	mg	Each	ECOPACK® 2	
	Comment	ECOPACK® 2 is STMicroelectronics trade name for ROHS compliant device without Brominated and Chlorinated compound (900ppm) and without Antimony oxide flame retardant		

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles	 life.augmented	
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NAC	Tin (Sn), matte	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
QFN	3x3x0.95	6	flat	
Comment	Package: YG VFDFPN 6 3X3 0,95 PITCH; MDF valid for LD39150PU33R			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	true
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	false
Exemption Id.	Description

QueryList : REACH-15th January 2018				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

24.400

Material Composition Declaration						Mfr Item Name	MYYG*UTS8AA6	24.4000				
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	Other inorganic materials	1.724	mg	supplier	die	Silicon (Si)	7440-21-3		1.618	mg	938515	66311
				supplier	metallization	Aluminium (Al)	7429-90-5		0.014	mg	8121	574
				supplier	metallization	Tungsten (W)	7440-33-7		0.023	mg	13341	943
				supplier	Passivation	Silicon Nitride	12033-89-5		0.003	mg	1740	123
				supplier	Passivation	Silicon Oxide	7631-86-9		0.033	mg	19142	1352
				supplier	back side metallization	Chromium (Cr)	7440-47-3		0.001	mg	580	41
				supplier	back side metallization	Gold (Au)	7440-57-5		0.003	mg	1740	123
				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.011	mg	6381	451
				supplier	glass coating	Glass: Silicon Dioxide	7631-86-9		0.001	mg	580	41
				supplier	polymer die coating	PIX1 Gamma-butyrolactone	96-48-0		0.017	mg	9861	697
Leadframe	Copper & its alloys	8.468	mg	supplier	Alloy	Copper (Cu)	7440-50-8		8.178	mg	965753	335164
				supplier	Alloy	Iron (Fe)	7439-89-6		0.191	mg	22556	7828
				supplier	Alloy	Lead (Pb)	7439-92-1		0.001	mg	118	41
				supplier	Alloy	Iron Phosphide (Fe2P)	1310-43-6		0.002	mg	236	82
				supplier	Alloy	Zinc (Zn)	7440-66-6		0.011	mg	1299	451
				supplier	Alloy	Silver (Ag)	7440-22-4		0.085	mg	10038	3484
Die attach	Other organic materials	0.091	mg	supplier	glue	Silver (Ag)	7440-22-4		0.062	mg	681319	2541
				supplier	glue	methylene diacrylate	42594-17-2		0.023	mg	252747	943
				supplier	glue	Dicyclopentenyloxyethyl methacrylate	68586-19-6		0.003	mg	32967	123
				supplier	glue	Polymer of Polybutadiene + Anhydride	Proprietary		0.003	mg	32967	123
Bonding wire	Other inorganic materials	0.081	mg	supplier	Wire	Gold (Au)	7440-57-5		0.081	mg	1000000	3320
Encapsulation	Other organic materials	13.840	mg	supplier	molding compound	Silica Fused	60676-86-0		12.969	mg	937066	531516
				supplier	molding compound	Epoxy Resin	25068-38-6		0.415	mg	29986	17008
				supplier	molding compound	Phenol Resin	29690-82-2		0.415	mg	29986	17008
				supplier	molding compound	Carbon Black	1333-86-4		0.041	mg	2962	1680
Finishing	Other inorganic materials	0.196	mg	supplier	Connection coating	Tin (Sn)	7440-31-5		0.196	mg	1000000	8033